

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (Currently Amended) A method of manufacturing a wiring board, comprising:

performing a plating process on a land, the land having a generally rectangular shape including at least one inwardly extending depression formed in a side thereof, the land being in a condition that a resist film having an opening exposing at least a center of the land is formed on a substrate with a wire having the land formed thereon, the substrate having a resist film formed thereon, the resist film being on the land and the wire and having an opening exposing at least a center of the land and a part of a periphery of the land corresponding to the at least one depression, the opening having a generally rectangular shape and being formed so that a ~~first~~first portion of an edge of the opening corresponding to the at least one depression is disposed on the substrate and a second portion of the edge of the opening is disposed on the land.

2. (Currently Amended) A method of manufacturing a wiring board, comprising

forming a resist film on a substrate with a wire having a land having a shape including a depression formed thereon, the resist film having an opening exposing at least a center of the land, so that, taking a smallest circumscribing rectangle of the land as a reference, every side of the rectangle is covered by the resist film while the depression of the land is partially exposed through the opening; and

performing a plating process on the land with the resist film formed.

3. (Currently Amended) A method of manufacturing a wiring board, comprising:

forming a resist film on a substrate with a wire having a land formed thereon, the land having a generally rectangular shape including at least one inwardly extending depression formed in a side thereof, the resist film having being formed on the wire and the land with an opening exposing at least a part of a periphery of the land corresponding to the at least one depression and a center of the land, the opening having a generally rectangular shape and being formed so that a sum of a length of a first side-lengths of the periphery of the land which is covered by the resist film is larger than a sum of a second side which is lengths of the periphery of the land exposed through the opening; and

performing a plating process on the land with the resist film formed.

4-12. (Cancelled)

13. (Currently Amended) The method of manufacturing a wiring board according to Claim 2,

wherein ~~the land has a shape including a depression~~ the land has a generally rectangular shape, the depression extends inwardly from a side of the land, and the opening of the resist film has a generally rectangular shape corresponding to the shape of the land ~~is formed~~ so that the depression is partially exposed through the opening.

14-21. (Cancelled)